

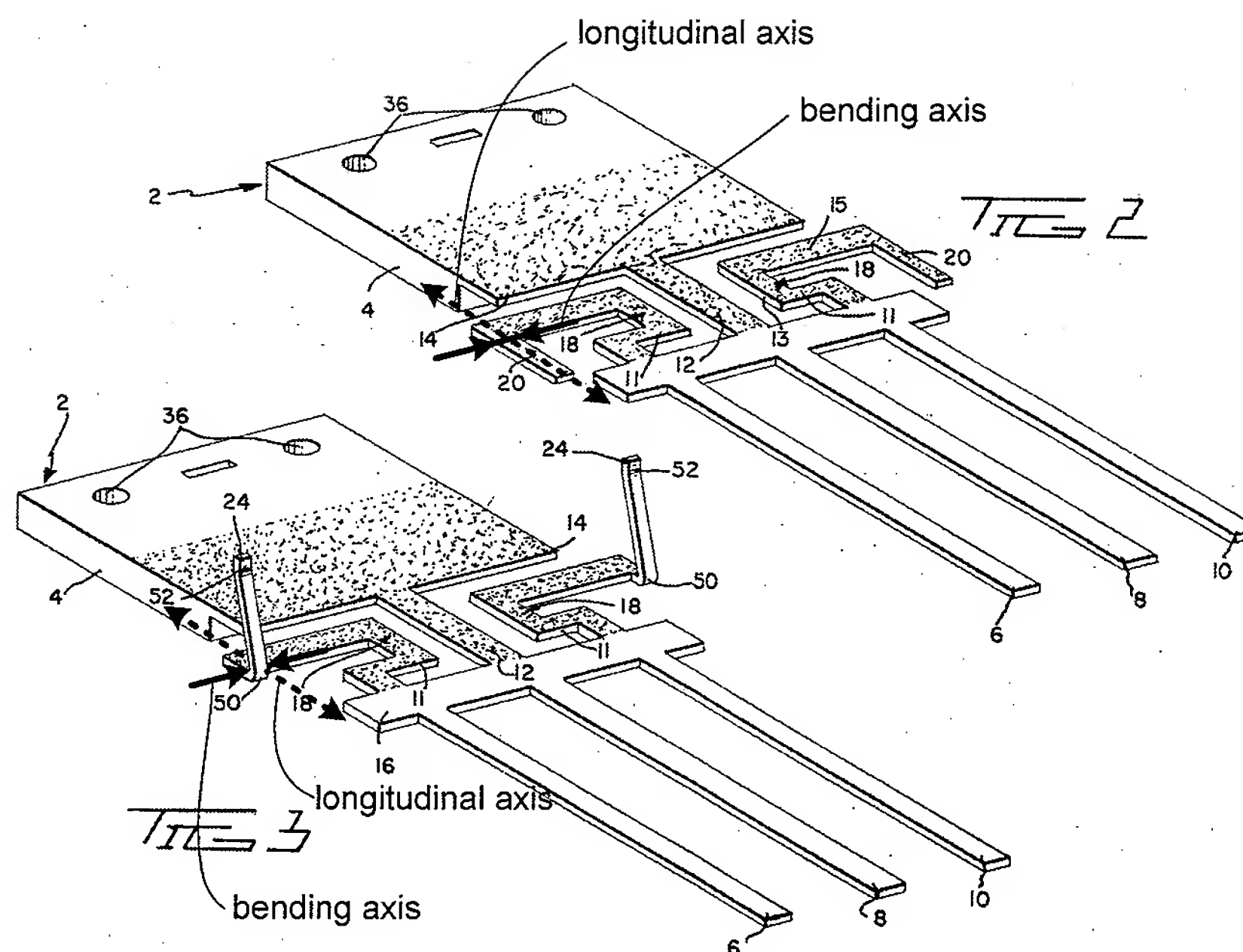
Remarks

Claims 1-10 and 12-16 are currently pending in the patent application. For the reasons and arguments set forth below, Applicant respectfully submits that the claimed invention is allowable over the cited references.

In the instant Office Action dated February 12, 2008, the following objection and rejections are noted: claims 1-7, 9-13 and 15-16 stand rejected under 35 U.S.C. § 102(b) over Heinlen (U.S. Patent 3,736,367); and claims 8 and 14 stand rejected under 35 U.S.C. § 103(a) over Heinlen as applied to claim 13 above in view of Sakamoto (U.S. Patent No. 6,975,022). Applicant traverses these rejections.

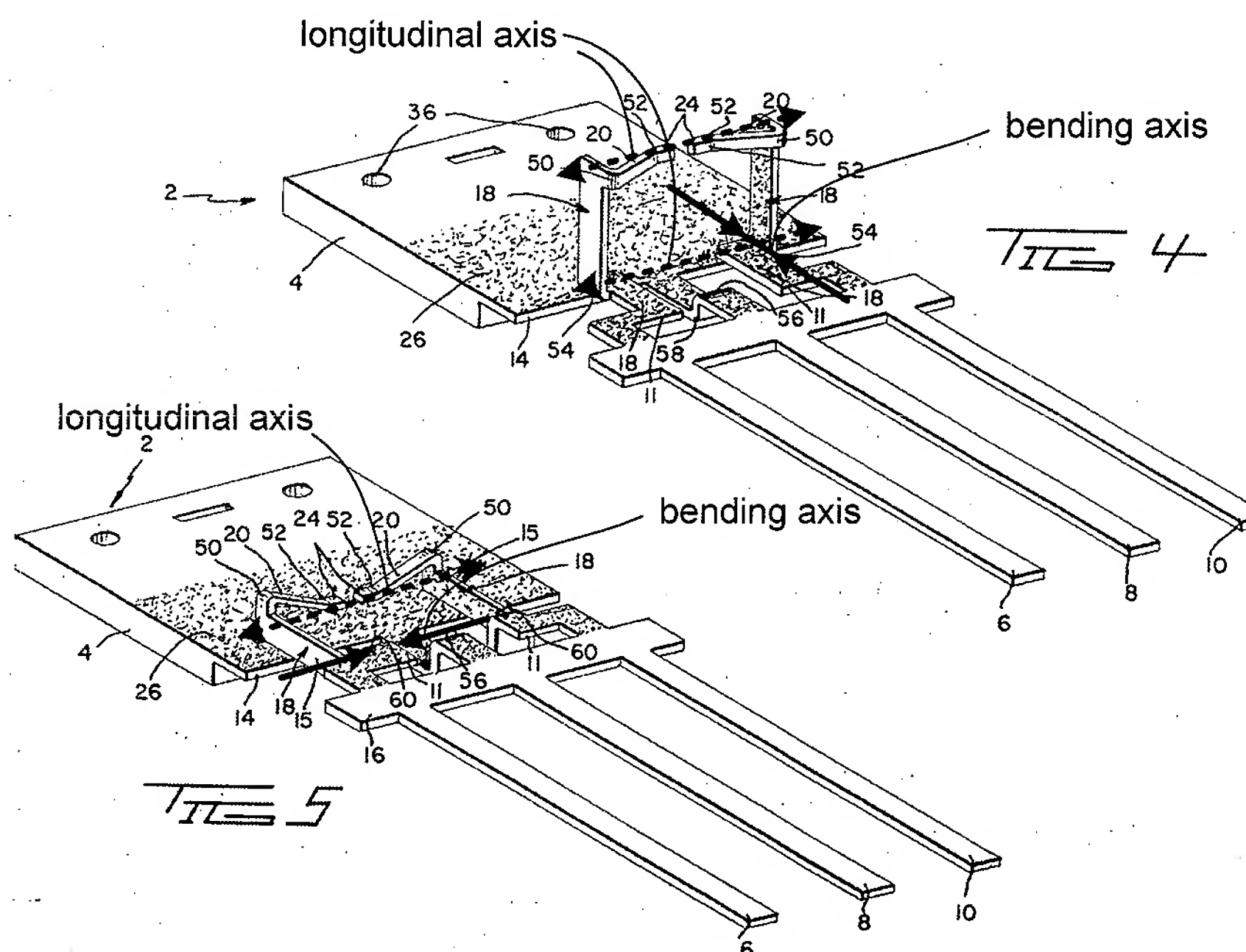
Applicant notes that claim 11 was previously cancelled.

Applicant submits that the Heinlen reference appears to include no teaching or disclosure to correspond to the claimed aspects directed to the end portion of the second connection conductor being brought to a position opposite the position of the semiconductor element by bending along a bending axis that is at an oblique angle (*i.e.*, an angle other than a right angle) with respect to the longitudinal axis of the end portion. All of the bending axes shown by Heinlen form right angles with respect to the longitudinal axis of the bent portion. To illustrate, Applicant reproduces Heinlen's Figs. 2-5 below, indicating various examples of pairs of bending axes and longitudinal axes, each pair of axes forming right angles.



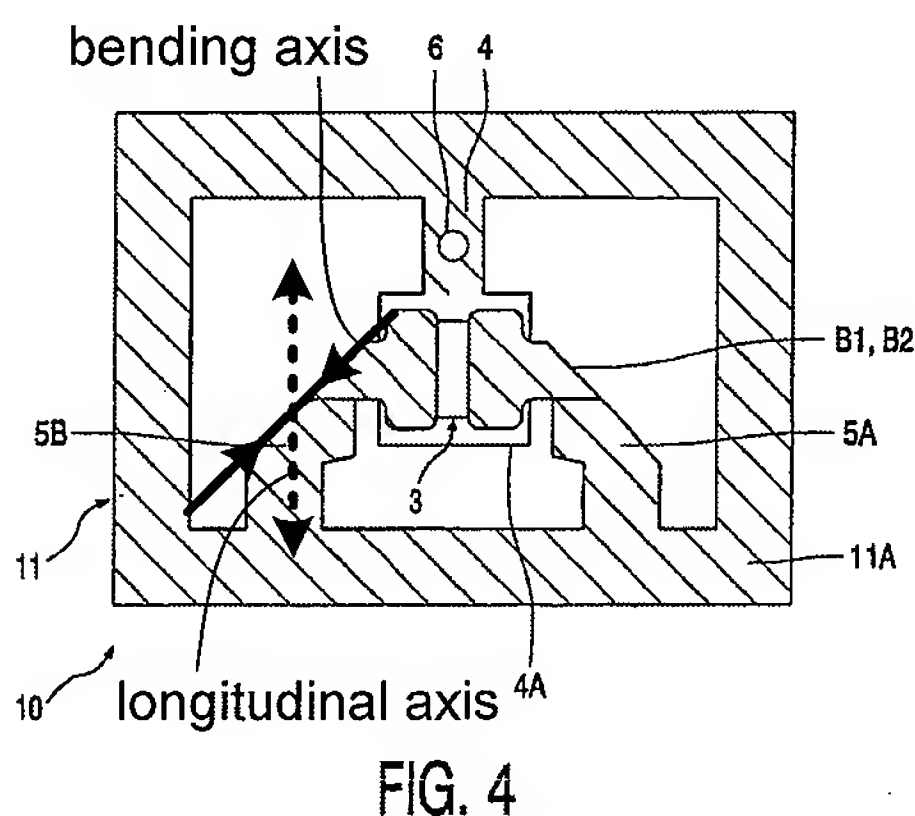
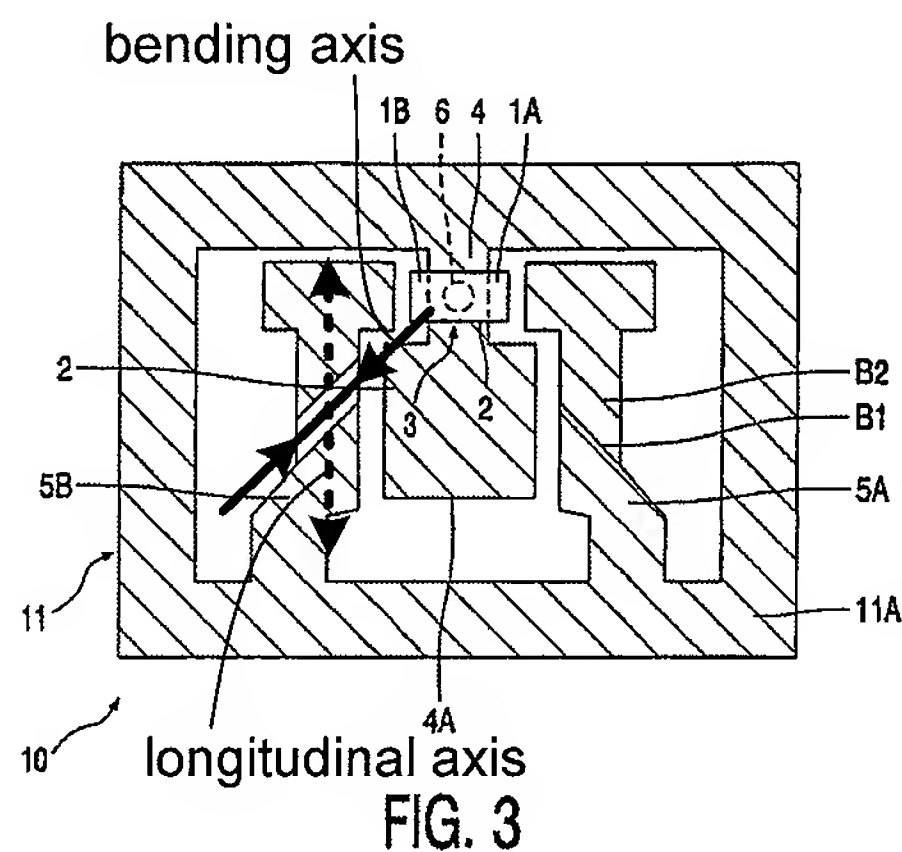
Heinlen's Figs. 2 and 3

As can be seen, the Heinlen reference teaches a specific series of bends that result in the tip 24 being located above heat sink 4, each of these bends is along an axis that is either perpendicular or parallel to the longitudinal axis referenced to the tips 24.



Heinlen's Figs. 4 and 5

In response, the Examiner stated that, “Using the same logic as provided by the applicant, the bending axis provided by applicant’s drawings, namely Fig. 3-4, would also be along a perpendicular axis.” This statement is demonstrably untrue by simple inspection of Applicant’s Figs. 3 and 4, which are reproduced below, and also indicating the bending axis and longitudinal axis forming an oblique angle.



Applicant’s Figs. 3 and 4

The Examiner further responded to Applicant’s arguments by stating, “Referring to Fig. 4 [of Heinlen], applicant states that ‘contact arm 20 is bent upward at bend 50, in the transition between Fig. 4 and Fig. 5,’ the examiner fails to see where there is an upward bend at all.” Applicant submits that Applicant’s observations are consistent with the entire progression from Fig. 2 to Fig. 5 of Heinlen, and consistent with the description provided by Heinlen (*see, e.g.*, Col. 3:39-40).

For these reasons, and for the reasons provided in Applicant's Response of October 31, 2007, Applicant submits that the § 102(b) rejection of claims 1-7, 9-13 and 15-16 over Heinlen is improper. Reconsideration and withdrawal of the rejection is therefore requested.

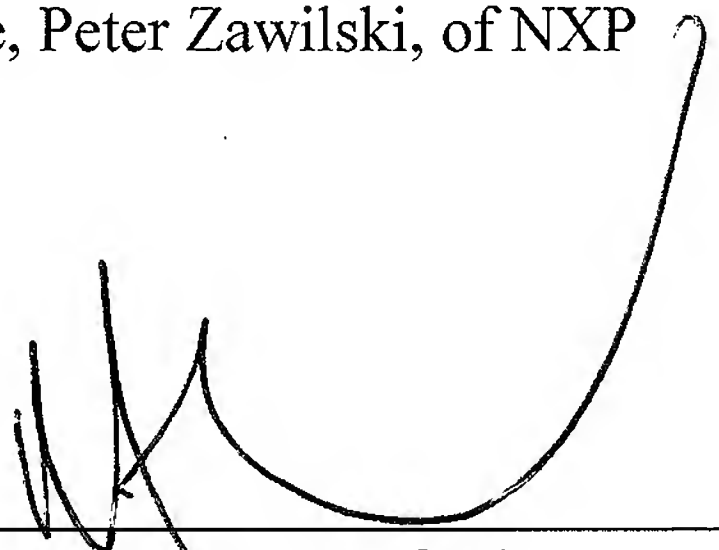
Applicant respectfully traverses the § 103(a) rejection of claims 8 and 14 over Heinlen in view of Sakamoto because the Heinlen reference does not correspond to the claimed invention as discussed above, and because the Sakamoto reference appears to provide no teaching to overcome these deficiencies. In at least this regard, the § 103(a) rejection is improper, and Applicant therefore requests that the rejection of claims 8 and 14 be withdrawn.

In view of the remarks above, Applicant believes that each of the rejections has been overcome and the application is in condition for allowance. Should there be any remaining issues that could be readily addressed over the telephone, the Examiner is asked to contact the agent overseeing the application file, Peter Zawilski, of NXP Corporation at (408) 474-9063 (or the undersigned).

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